



## Material Content Data Sheet



<b>Sales Product Name</b>		1EDI30J12CP		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA001056342							
<b>Package</b>		PG-DSO-19-4		<b>Weight*</b>		581.12 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.203	0.55	0.55	5512	5512	
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		69		
	non noble metal	zinc	7440-66-6	0.160	0.03		275		
	non noble metal	iron	7439-89-6	3.200	0.55		5506		
wire	non noble metal	copper	7440-50-8	129.929	22.36	22.95	223586	229436	
	noble metal	gold	7440-57-5	0.478	0.08	0.08	822	822	
	encapsulation	organic material	carbon black	1333-86-4	1.319	0.23		2269	
plastics	plastics	epoxy resin	-	42.642	7.34		73379		
	inorganic material	silicondioxide	60676-86-0	395.648	68.08	75.65	680839	756487	
	leadfinish	non noble metal	tin	7440-31-5	3.337	0.57	0.57	5742	5742
plating	noble metal	silver	7440-22-4	0.174	0.03	0.03	299	299	
glue	plastics	acrylic resin	-	0.218	0.04		374		
	noble metal	silver	7440-22-4	0.772	0.13	0.17	1328	1702	
*deviation	< 10%				Sum in total:		100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com